4, 5

FORM PTO-1595 (Rev. 6-93)



103393099

3. DEPARTMENT OF COMMERCE Patent and Trademark Office

	11.561
PATENTS ONLY	
	Attorney Docket No.: 48370-0034
To the Commissioner for Patents  ATTN: MAIL STOP ASSIGNMENT RECORDATION SERVICES  Please record the attached original documents or copy thereof.	
1. Name of conveying party(ies):	2. Name and address of receiving party(ies):
1) Tomoharu FUJII	Name: Shinko Electric Industries Co., Ltd.
Additional names of conveying party(ies) attached?  Yes No	Address: 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan
3. Nature of conveyance:	Additional name(s) & address(es) attached?
Assignment	☐ Yes  ☐ No
4. New Application number(s) or patent number(s): NEW APPLICATION	
If this document is being filed together with a new application the execution date of the application is:	
(1) Decem	aber 20, 2006
A. Patent Application No.(s)  B. Patent No.(s)	
Additional numbers attached:   Yes   No	
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1
Name: John G. Smith	7. Total fee (37 C.F.R. §3.41): <u>\$40.00</u> ⊠ Enclosed
Internal Address: DRINKER BIDDLE & REATH LLP	Authorized to be charged to Deposit Account 50-0573
Customer No. 55694	8. Deposit Account No. 50-0573 (Attach duplicate page if paying by deposit account)
Street Address: 1500 K. Street, NW., Suite 1100 City: Washington State: D.C. Zip: 20005-1209	
9. Statement and Signature To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true	
copy of the original document.	
John G. Smith Reg. No. 33,818	gnature 03/28/2007 JADD01 Date 0023 11727547 gumber of pages including cover sheet, attachments and documents: 213
55 7 0.00.1	

## **ATTORNEY DOCKET NO.:**

SOLE/JOINT INVENTION (U.S. Rights Only)

## ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled: MANUFACTURING METHOD OF WIRING SUBSTRATE AND MANUFACTURING METHO OF SEMICONDUCTOR DEVICE for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Serial No. \_\_\_\_); and WHEREAS, Shinko Electric Industries Co., Ltd., a corporation of Japan, whose post office address is 80, Oshimada-machi, Nagano-shi, Nagano, 381-2287, Japan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application; NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment; AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns. AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. \_\_\_\_\_\_\_ filed \_) the filing date and application number of said application when known. IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s). Date Assignor's Signature Full Name of Sole or First Assignor 06.12.20 Fomoharu Friji Tomoharu FUJII Address c/o Shinko Electric Industries Co., Ltd., 80, Oshimada-Machi, Nagano-Citizenship Japan shi, Nagano, 381-2287, Japan Date Assignor's Signature Full Name of Second Assignor Citizenship Address

⊠ No

1-WA/1632828.2

PATENT REEL: 019158 FRAME: 0633

RECORDED: 03/27/2007

Names of additional inventors attached Yes